

RESEARCH PUBLICATIONS

- 1) **Ye Zhu**, Chong Wei Tan, Shen Lin Chua, Yu Dian Lim, Boris Vaisband, Beng Kang Tay, Eby G. Friedman, Chuan Seng Tan, “Assembly Process and Electrical Property of Top-Transferred Graphene on Carbon Nanotubes for Carbon-Based Three-Dimensional Interconnects”, *Carbon*, submitted
- 2) Chong Wei Tan, **Ye Zhu**, Shen Lin Chua, Maziar Shakerzadeh, Chuan Seng Tan and Beng Kang Tay, “Electrical properties of FCVA deposited nano-crystalline graphitic carbon thin films with in-situ treatment techniques”, *Eur. Phys. J. Appl. Phys.*, DOI: 10.1051/epjap/2019180097
- 3) **Ye Zhu**, Chong Wei Tan, Shen Lin Chua, Yu Dian Lim, Beng Kang Tay, Chuan Seng Tan, “Growth and Fabrication of Carbon-Based Three-Dimensional Heterostructure in Through-Silicon Vias (TSVs) for 3D Interconnects”, *IEEE 19th Electronics Packaging Technology Conference (EPTC)*, 2017, pp. 1-5.
- 4) **Ye Zhu**, Kaushik Ghosh, Hong Yu Li, Yiheng Lin, Chuan Seng Tan, Guangrui (Maggie) Xia, “On the Origins of Near-Surface Stresses in Silicon around Cu-filled and CNT-filled Through Silicon Vias”, *Semiconductor Science and Technology*, vol. 31, 2016, p. 055008.
- 5) **Ye Zhu**, Jiye Zhang, Hong Yu Li, Chuan Seng Tan and Guangrui (Maggie) Xia, “Study of Near-surface Stresses in Silicon around Through Silicon Vias at Elevated Temperatures by Raman Spectroscopy and Simulations.” *IEEE Transactions on Device and Materials Reliability*, vol. 15, 2015, pp.142-148.